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PRIMA-SOLDER

EG8050

Stress-Free
One or Two Component
Reworkable
Epoxy Paste Adhesive

IDEAL FOR:

- **Large Area Die**
- **Substrate/Component**
- **Reworkability**
- **Mismatched CTE's**
- **Solder Replacement**

DESCRIPTION:

EG8050 is an electrically conductive, silver filled epoxy which exhibits outstanding flexibility for bonding materials with highly mismatched CTE's (i.e., alumina to aluminum, silicon to copper).

It can be readily reworked at 80-100ºC and is ideal for applications such as large area die attach and substrate attach because of it's ability to bond materials with highly mismatched CTE.

AVAILABILITY:

EG8050 is available in syringes for automatic needle dispense applications or in jars. Both viscosity and thixotropic index can be modified to your specific needs. EG8050 can be premixed and frozen.

APPLICATION PROCEDURES:

(1) Mix adhesive in 1:1 ratio. (Note: In kit form, Viscosity of Part A > Viscosity of Part B)

(2) Dispense adhesive onto clean substrate.

(3) Cure according to one of the recommended schedules.

**If material is premixed and frozen, thaw for 30 minutes and cure according to one of the recommended schedules.

TYPICAL PROPERTIES*

Electrical Resistivity (150 ºC/ 60 min)	**<4x10 $^{-4}$ ohm-cm**
Dielectric Strength (Volts/mil)	**N/A**
Glass Transition Temp.(ºC)	**-20**
Current Carrying Capabilities	**35 Amp/mm²**
Lap-Shear Strength	**1000 psi**
	6.9 N/mm²
Device Push-off Strength	**1800 psi**
	12.4 N/mm²
Cured Density (gm/cc)	**4.0**
Thermal Conductivity	**55 Btu-in/hr-ft²-ºF**
	7.9 W/m-ºC
Linear Thermal Expansion Coeff. (ppm/ºC)	**120**
Maximum Continuous Operation Temp. (ºC)	**130**
Avg. Viscosity(0.5 rpm, 24ºC) (Brookfield DV-1, spindle CP51)	**190,000 cp**

* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:

Temperature	Time
25ºC	120 hr
80ºC	8 hr
125ºC	2 hr
150ºC	1 hr

SHELF LIFE:

Storage temperature	Shelf Life
**25ºC	1 yr in original sealed package

**Shelf life is for unmixed components. If premixed: -40ºC for 6 months in original sealed package. After mixing, pot life is 4 hours at 25ºC.